



## AGENDA – MacDermid Enthone Electronics Solutions Seminar in Japan

9:00 – 9:30

Registration

9:30 – 9:40



### Opening Remarks

Julian Bashore, General Manager - Japan

9:40 – 10:05



### Technology Roadmap: What to Expect

Joe D'Ambrisi, Sr. Vice President – Electronics Solutions  
Interpreter: Naomi Ando

10:05 – 10:45



### Advances in Via Fill and Acid Copper Technologies

Bill Bowerman, Director – Metallization  
Interpreter: Yasuhiro Mikami

10:45 – 10:55

Coffee Break

10:55 – 11:30



### Success in Semi Additive Process and IC Substrate Chemistries

Jim Watkowski, Vice President, Innovation  
Interpreter: Kayono Serizawa

11:30 – 12:00



### Transition of Final Finish: Tin, OSP and ENIG

John Swanson, Director of OEM and Final Finishes  
Interpreter: Naomi Ariyoshi

12:00 – 13:00

Lunch Reception



# AGENDA – MacDermid Enthone Electronics Solutions Seminar in Japan

13:00 – 13:30



## Rigid Applications of Direct Metallization

Bill Bowerman, Director of Metallization  
Interpreter: Naotaka Yamamoto

13:30 – 14:00



## Latest OEM Trends in Automotive Electronics

John Swanson, Director of OEM and Final Finishes  
Interpreter: Masaomi Aoki

14:00 – 14:30



## Trends in Automotive Electronics and Challenges in Surface Mount Technology

Toshihiro Miyake, Ph.D.  
Project Manager, Basis Electronics R&D Division – Denso Corporation

14:30 – 14:50



## Alpha Assembly Solutions Presents Next-Generation Soldering Material Selection

Mutsuharu Tsunoda  
Director - Japan Research Center, Alpha Assembly Solutions

14:50 – 15:00



## Closing Remarks

Jim Watkowski, Vice President, Innovation  
Interpreter: Heath Suzuki

15:00 – 17:30

GDAC Japan Lab Tour

17:30 – 19:30



## Evening Banquet

Remarks: Don Cullen, Director of Marketing Communications